	CONNECTING CS INDUSTRIES® International and Pan	PC, Bannockb	urn, Illinois. A	Il rights reserved un ntions.	nder both	This docume level parts, t	ent is a declarat he declaration	ion of the encompas	e substances sses all low	s within the r er level mate	nanufacture rials for wh	er listed it nich the m	em. Note:	if the item is an as or has engineering	sembly with lowe responsibility.	
1752-21.1					Form Type Distribute	 Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater 					ous Materia	ials and Mfg Information				
Supplier	r Information															
Company	name*	Company un	Company unique ID			Unique ID Authority					Response Date*					
onsemi												2024-04-19				
Contact N	lame	Title - Contact]	Phone - Contact*					Email - Contact*					
Product-Env-Stewards			Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
uthorize	ed Representative*		Title - Representative]	Phone - Representative*				Email - Representative*					
Product-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
	Requester Item Number Mfr Item MC78124						Effective Date	e Version Manufacturing Site		ng Site	V	Veight*	UOM	Unit Type		
							2024-04-19 CNC			1	962.0	mg	Each			
/anufa	cturing Proccess Informat	ion		1				- 1								
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-020 M		-STD-020 MSI	L Rating	Peak Process Body Temperat		ure Max Time at Peak Tem		Temperatu	ire Num	ber of Reflow Cyc	eles		
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		С	30		second	is 3					
omments	5															
or more	information regarding material of	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.55	mg	Supplier	Silicon (Si)	7440-21-3		3.55	mg
Die Attach	82.92	mg	А	Lead (Pb)	7439-92-1	7a	78.774	mg
			Supplier	Tin (Sn)	7440-31-5		4.146	mg
Lead Frame	1299.13	mg	В	Nickel (Ni)	7440-02-0		0.6496	mg
			Supplier	Iron (Fe)	7439-89-6		1.2991	mg
			Supplier	Copper (Cu)	7440-50-8		1296.7916	mg
			Supplier	Phosphorus (P)	7723-14-0		0.3896	mg
Mold Compound-Black	543.9	mg		Phenolic Resin	proprietary data		32.634	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		54.39	mg
			Supplier	Carbon Black (C)	1333-86-4		2.7195	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		40.7925	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		413.364	mg
Plating	31.13	mg	Supplier	Tin (Sn)	7440-31-5		31.13	mg
Wire Bond - Cu	1.37	mg	Supplier	Copper (Cu)	7440-50-8		1.37	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3